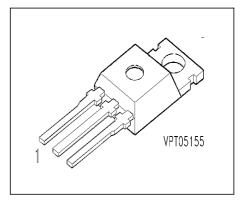


## **BUZ 172**

## **SIPMOS** ® **Power Transistor**

- P channel
- Enhancement mode
- Avalanche rated



Pin 1	Pin 2	Pin 3
G	D	S

Туре	$V_{\rm DS}$	I <sub>D</sub>	R <sub>DS(on)</sub>	Package	Ordering Code
BUZ 172	-100 V	-5.5 A	0.6 Ω	TO-220 AB	C67078-S1451-A2

### **Maximum Ratings**

Parameter	Symbol	Values	Unit
Continuous drain current	I <sub>D</sub>		Α
$T_{\rm C}$ = 37 °C		-5.5	
Pulsed drain current	I <sub>Dpuls</sub>		
$T_{\rm C}$ = 25 °C		-22	
Avalanche energy, single pulse	E <sub>AS</sub>		mJ
$I_{D}$ = -5.5 A, $V_{DD}$ = -25 V, $R_{GS}$ = 25 $\Omega$			
$L = 8.4 \text{ mH}, T_{j} = 25 ^{\circ}\text{C}$		170	
Gate source voltage	$V_{GS}$	± 20	V
Power dissipation	P <sub>tot</sub>		W
$T_{\rm C}$ = 25 °C		40	
Operating temperature	$  au_{ m j} $	-55 <b>+</b> 150	°C
Storage temperature	$T_{ m stg}$	-55 <b>+</b> 150	
Thermal resistance, chip case	R <sub>thJC</sub>	≤ 3.1	K/W
Thermal resistance, chip to ambient	$R_{thJA}$	≤ 75	
DIN humidity category, DIN 40 040		Е	
IEC climatic category, DIN IEC 68-1		55 / 150 / 56	



# **Electrical Characteristics,** at $T_j = 25$ °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Drain- source breakdown voltage	V <sub>(BR)DSS</sub>				V
$V_{\rm GS}$ = 0 V, $I_{\rm D}$ = -0.25 mA, $T_{\rm j}$ = 25 °C		-100	-	-	
Gate threshold voltage	V <sub>GS(th)</sub>				
$V_{\text{GS}} = V_{\text{DS}}$ , $I_{\text{D}} = 1 \text{ mA}$		-2.1	-3	-4	
Zero gate voltage drain current	I <sub>DSS</sub>				μΑ
$V_{\rm DS}$ = -100 V, $V_{\rm GS}$ = 0 V, $T_{\rm j}$ = 25 °C		-	-0.1	-1	
$V_{\rm DS}$ = -100 V, $V_{\rm GS}$ = 0 V, $T_{\rm j}$ = 125 °C		-	-10	-100	
Gate-source leakage current	I <sub>GSS</sub>				nA
$V_{GS} = -20 \text{ V}, \ V_{DS} = 0 \text{ V}$		-	-10	-100	
Drain-Source on-resistance	R <sub>DS(on)</sub>				Ω
$V_{\rm GS}$ = -10 V, $I_{\rm D}$ = -3.7 A		-	0.4	0.6	



# **Electrical Characteristics,** at $T_j = 25$ °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Dynamic Characteristics					
Transconductance	g <sub>fs</sub>				S
$V_{\rm DS} \ge 2 * I_{\rm D} * R_{\rm DS(on)max}, I_{\rm D} = -3.7 \text{ A}$		1	2	-	
Input capacitance	$C_{iss}$				pF
$V_{GS} = 0 \text{ V}, \ V_{DS} = -25 \text{ V}, \ f = 1 \text{ MHz}$		-	800	1200	
Output capacitance	$C_{\rm oss}$				
$V_{GS} = 0 \text{ V}, \ V_{DS} = -25 \text{ V}, \ f = 1 \text{ MHz}$		-	220	330	
Reverse transfer capacitance	$C_{rss}$				
$V_{GS} = 0 \text{ V}, \ V_{DS} = -25 \text{ V}, \ f = 1 \text{ MHz}$		-	90	140	
Turn-on delay time	$t_{d(on)}$				ns
$V_{\rm DD}$ = -30 V, $V_{\rm GS}$ = -10 V, $I_{\rm D}$ = -2.8 A					
$R_{\rm GS}$ = 50 $\Omega$		-	20	30	
Rise time	$t_{\rm r}$				
$V_{\rm DD}$ = -30 V, $V_{\rm GS}$ = -10 V, $I_{\rm D}$ = -2.8 A					
$R_{\rm GS}$ = 50 $\Omega$		-	120	180	
Turn-off delay time	t <sub>d(off)</sub>				
$V_{\rm DD}$ = -30 V, $V_{\rm GS}$ = -10 V, $I_{\rm D}$ = -2.8 A					
$R_{\rm GS}$ = 50 $\Omega$		-	70	90	
Fall time	<i>t</i> <sub>f</sub>				
$V_{\rm DD}$ = -30 V, $V_{\rm GS}$ = -10 V, $I_{\rm D}$ = -2.8 A					
$R_{\rm GS}$ = 50 $\Omega$		-	55	75	



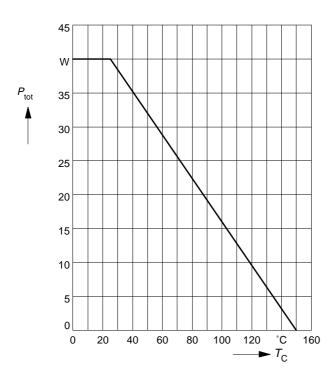
## **Electrical Characteristics**, at $T_j = 25$ °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Reverse Diode					
Inverse diode continuous forward current	IS				А
$T_{\rm C}$ = 25 °C		-	-	-5.5	
Inverse diode direct current,pulsed	/ <sub>SM</sub>				
<i>T</i> <sub>C</sub> = 25 °C		-	-	-22	
Inverse diode forward voltage	$V_{\mathrm{SD}}$				V
$V_{GS} = 0 \text{ V}, I_{F} = -11 \text{ A}$		-	-1	-1.3	
Reverse recovery time	t <sub>rr</sub>				ns
$V_{R} = -30 \text{ V}, I_{F} = I_{S}, di_{F}/dt = 100 \text{ A/}\mu\text{s}$		-	200	-	
Reverse recovery charge	$Q_{\rm rr}$				μC
$V_{R} = -30 \text{ V}, I_{F} = I_{S}, di_{F}/dt = 100 \text{ A/}\mu\text{s}$		-	0.75	-	



### **Power dissipation**

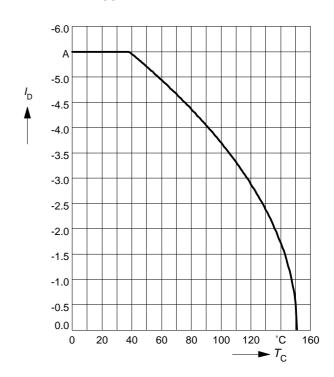
$$P_{\mathsf{tot}} = f(T_{\mathsf{C}})$$



#### **Drain current**

$$I_{\mathsf{D}} = f(T_{\mathsf{C}})$$

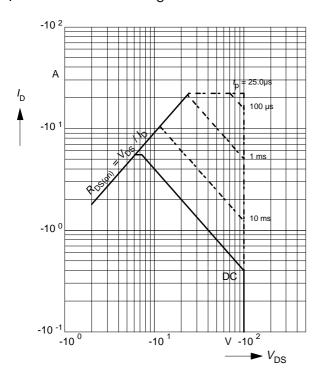
parameter:  $V_{GS} \ge -10 \text{ V}$ 



## Safe operating area

$$I_{\mathsf{D}} = f(V_{\mathsf{DS}})$$

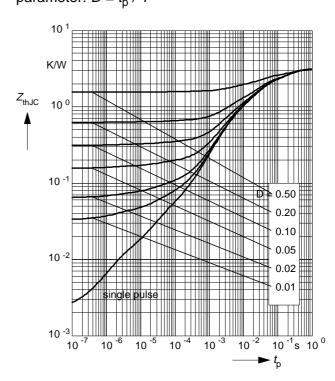
parameter: D = 0.01,  $T_C = 25$ °C



#### **Transient thermal impedance**

$$Z_{\text{th JC}} = f(t_{\text{p}})$$

parameter:  $D = t_p / T$ 

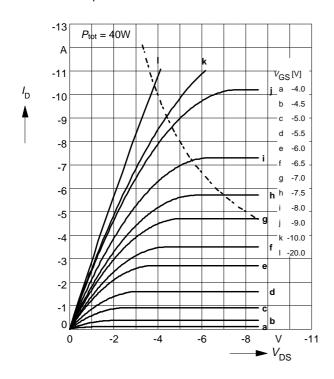




#### Typ. output characteristics

 $I_{\mathsf{D}} = f(V_{\mathsf{DS}})$ 

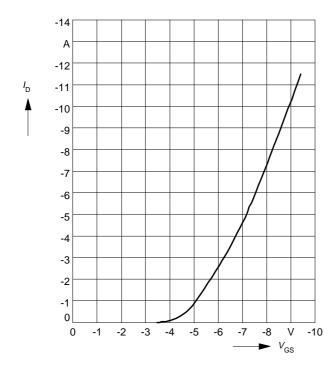
parameter:  $t_p = 80 \mu s$ 



## Typ. transfer characteristics $I_{D} = f(V_{GS})$

parameter:  $t_p = 80 \mu s$ 

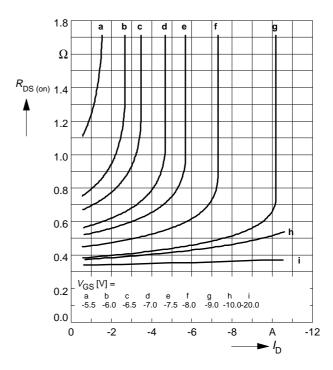
 $V_{DS} \ge 2 \times I_D \times R_{DS(on)max}$ 



#### Typ. drain-source on-resistance

 $R_{\mathrm{DS (on)}} = f(I_{\mathrm{D}})$ 

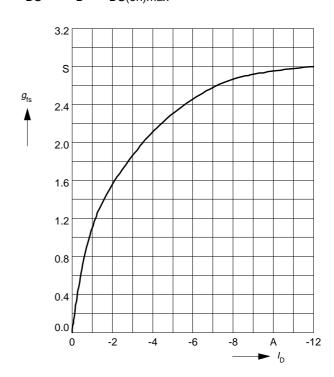
parameter:  $V_{\rm GS}$ 



#### Typ. forward transconductance $g_{fs} = f(I_D)$

parameter:  $t_p = 80 \mu s$ ,

 $V_{DS} \ge 2 \times I_D \times R_{DS(on)max}$ 

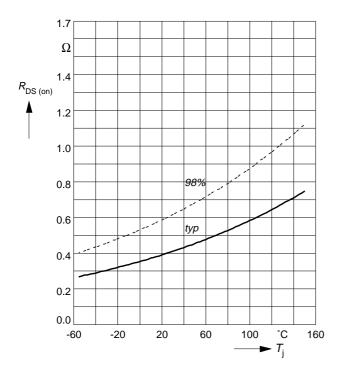




#### **Drain-source on-resistance**

 $R_{DS (on)} = f(T_j)$ 

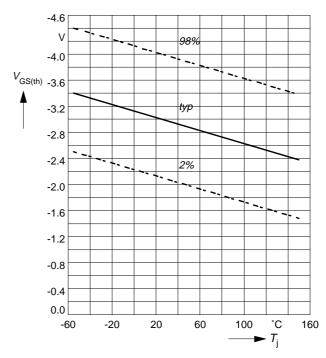
parameter:  $I_D$  = -3.7 A,  $V_{GS}$  = -10 V



#### Gate threshold voltage

 $V_{GS (th)} = f(T_j)$ 

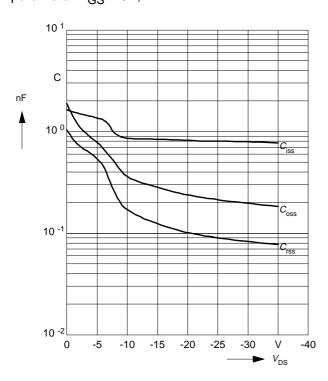
parameter:  $V_{GS} = V_{DS}$ ,  $I_D = 1 \text{ mA}$ 



#### Typ. capacitances

 $C = f(V_{DS})$ 

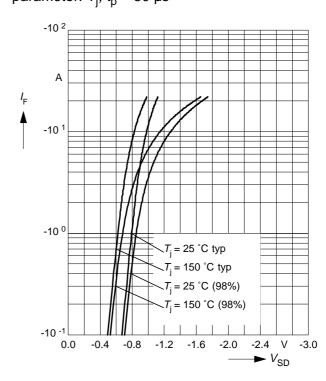
parameter:  $V_{GS} = 0V$ , f = 1MHz



#### Forward characteristics of reverse diode

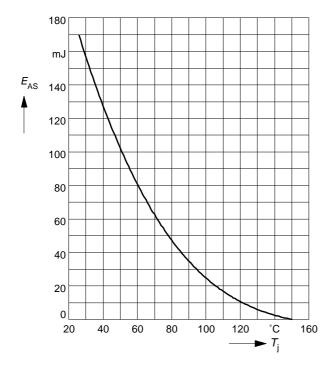
 $I_{\mathsf{F}} = f(V_{\mathsf{SD}})$ 

parameter:  $T_i$ ,  $t_p = 80 \mu s$ 



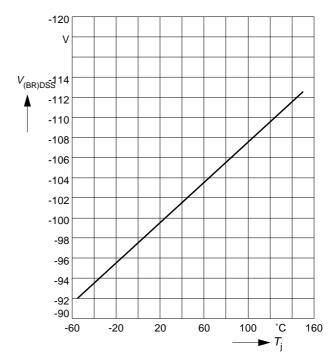


# Avalanche energy $E_{\rm AS} = f(T_{\rm j})$ parameter: $I_{\rm D}$ = -5.5 A, $V_{\rm DD}$ = -25 V $R_{\rm GS}$ = 25 $\Omega$ , L = 8.4 mH



#### Drain-source breakdown voltage

$$V_{(\mathsf{BR})\mathsf{DSS}} = f(T_{\mathsf{j}})$$



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